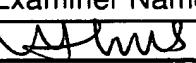


# ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	SOLDER INTERCONNECTION ARRAY WITH OPTIMAL MECHANICAL INTEGRITY						
Application Number:	10/711,501						
Confirmation Number:							
First Named Applicant:	Glenn Daves						
Attorney Docket Number:	FIS920040002US1						
Art Unit:	1725						
Examiner:							
Search string:	( 5060844 or 5784261 or 6015722 or 6048656 or 6177728 or 6294271 or 6310120 or 6506869 or 6572980 or 6586846 or 6333563 ).pn						
<b>US Patent Documents</b>							
<b>Note: Applicant is not required to submit a paper copy of cited US Patent Documents</b>							
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
AM	1	5060844	1991-10-29	Behun, et al.			
	2	5784261	1998-07-21	Pedder			
	3	6015722	2000-01-18	Banks, et al.			
	4	6048656	2000-04-11	Akram, et al.			
	5	6177728	2001-01-23	Susko, et al.			
	6	6294271	2001-09-25	Sumita, et al.			
	7	6310120	2001-10-30	Shiobara, et al.			
	8	6506869	2003-01-14	Yamaguchi, et al.			
	9	6572980	2003-06-03	Klemarczyk, et al.			
	10	6586846	2003-07-01	Ho			
AM	11	6333563	2001-12-25	Jackson, et al.			
<b>Signature</b>							
Examiner Name				Date			
				10/03/2006			